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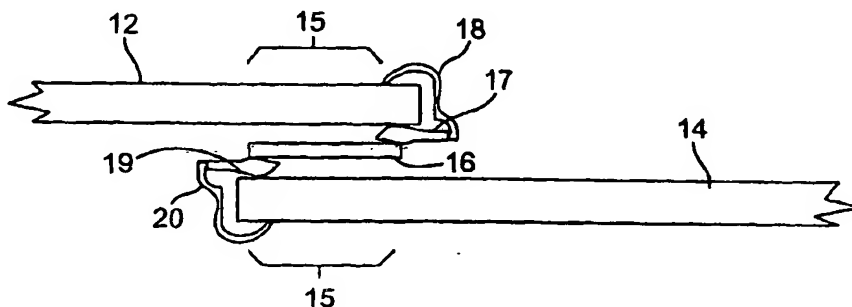
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(54) Title: METHOD FOR BONDING THERMOPLASTIC OR THERMOSET POLYMERIC MATERIALS UTILIZING VOLT-  
AGE APPLIED TO CONDUCTIVE MATERIAL.



(57) Abstract: A method for bonding or joining thermoplastic or thermoset polymeric materials is provided which comprises applying a layer of conductive material (16) at a joint or between surfaces of thermoplastic or thermoset polymeric materials (12, 14), introducing a current so as to raise the temperature of the polymeric material above its melting point, maintaining the current for a time sufficient to allow the polymeric material to become molten and thereby form the joint or bond, and then removing the current and allowing the joint or bond (15) to cool. The method is advantageous in that it provides a simple and inexpensive means of bonding thermoplastic or thermoset polymeric materials with a minimum of materials and equipment. The method of the present invention can also be utilized so as to heat thermoplastic pipes and other devices made of thermoplastic materials.

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